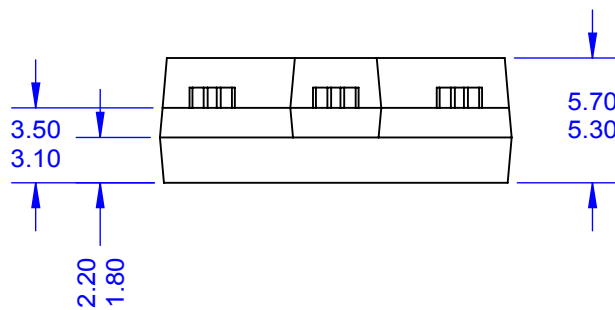
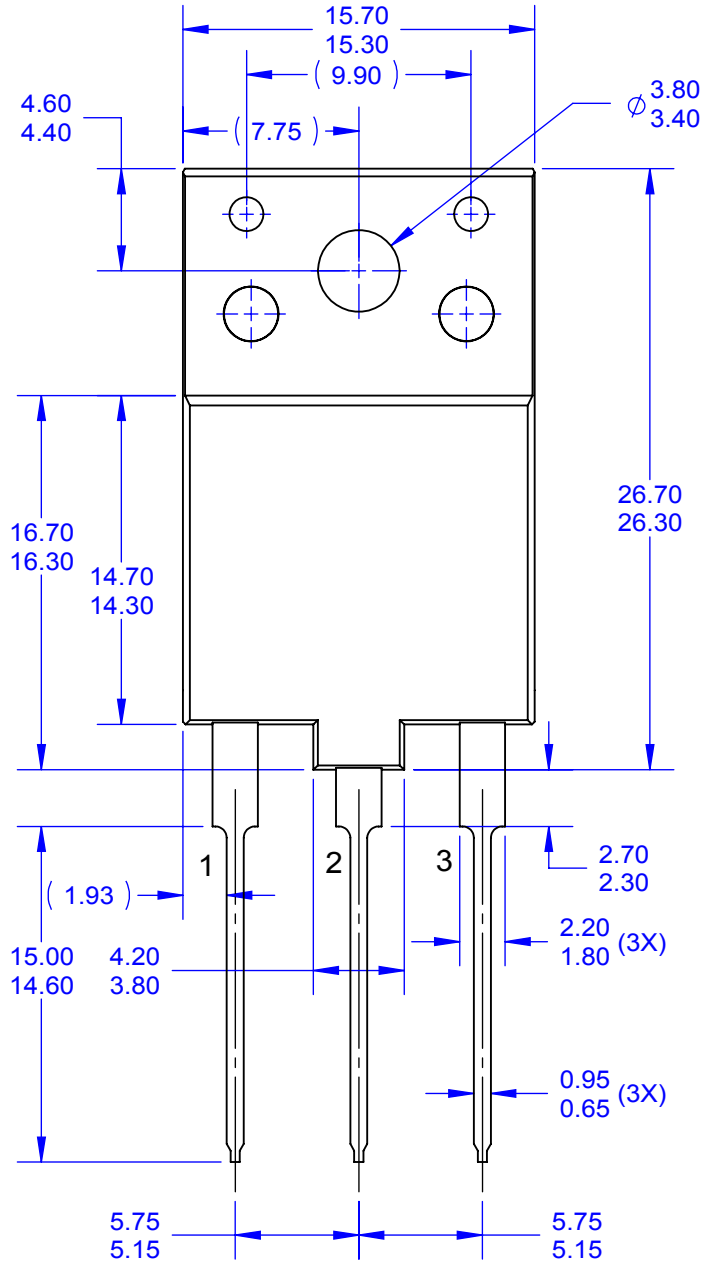


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REVISIONS

NBR	DESCRIPTION	DATE	BY/APP'D
1	RELEASED TO DCC	11DEC008	KHLEE/ SUZHOU



NOTES:

- A. THIS PACKAGE CONFORMS TO SC94 JEITA PACKAGING STANDARD.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. PIN 2 CONNECTS TO DAP.
- E. DRAWING FILE NAME: TO3PFA03REV1

APPROVALS		DATE		
DRAWN: BOBOY MALDO		11DEC08		
CHECKED: SD LEE				
APPROVED: BY HUANG				
APPROVED: HOWARD ALLEN			<b>TO3PF, MOLDED, 3LD, FULLPACK (AG)</b>	
PROJECTION				
SCALE	SIZE	DRAWING NUMBER	REV	
1:1	N/A	MKT-TO3PFA03	1	
FORMERLY: N/A			SHEET: 1 OF 1	